

TIDA-00373 REV E2 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		ISE4024	Any	Printed Circuit Board	
BL1	1		EA LED55X46-W	Electronic Assembly	LED Backlight, White	
C1	1	1000pF	202R18W102KV4E	Johanson Technology	CAP, CERM, 1000 pF, 2000 V, +/- 10%, X7R, 1206_190	1206_190
C2	1	0.01uF	08055C103JAT2A	AVX	CAP, CERM, 0.01 µF, 50 V, +/- 5%, X7R, 0805	0805
C3, C4	2	1uF	C1608X7R1C105K	TDK	CAP, CERM, 1 µF, 16 V, +/- 10%, X7R, 0603	0603
C5, C6, C8, C9,	13	1uF	C1608X7R1C105K	TDK	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	0603
C10, C11, C12,						
C13, C14, C15,						
C18, C20, C30						
C7	1	2.2uF	GRM188R71A225KE15D	MuRata	CAP, CERM, 2.2uF, 10V, +/-10%, X7R, 0603	0603
C16	1	1uF	UMK107AB7105KA-T	Taiyo Yuden	CAP, CERM, 1uF, 50V, +/-10%, X7R, 0603	0603
C17, C21, C28,	4	0.1uF	GRM155R71C104KA88D	MuRata	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	0402
C31						
C19, C22	2	10uF	C2012X7R0J106M125AB	TDK	CAP, CERM, 10 μF, 6.3 V, +/- 20%, X7R, 0805	0805
C23, C24, C25	3	2200pF	C1005X7R1H222K	TDK	CAP, CERM, 2200 pF, 50 V, +/- 10%, X7R, 0402	0402
C29	1	0.1uF	06033C104JAT2A	AVX	CAP, CERM, 0.1 µF, 25 V, +/- 5%, X7R, 0603	0603
D1	1	6V	SMBJ6.0CA	Littelfuse	Diode, TVS, Bi, 6 V, 600 W, SMB	SMB
D2	1	40V	NSR0240V2T1G	ON Semiconductor	Diode, Schottky, 40V, 0.25A, SOD-523	SOD-523
D3	1	5V	1SS315TPH3F	Toshiba	Diode, Schottky, 5V, 0.03A, SOD-323	SOD-323
D4	1	Green	SML-P12PTT86	Rohm	LED, Green, SMD	LED, 1x.2x.6mm
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902E	Keystone	Standoff, Hex, 1"L #4-40 Nylon	Standoff
H11, H12	2		NY PMS 256 0025 PH	B&F Fastener Supply	Nylon Screw, Panhead, Phillips, 2-56	
H13, H14	2		NY HN 256	B&F Fastener Supply	Nylon Nut, 2-56, 3/16"	
J1, J3	2		90120-0122	Molex	Header, 100mil, 2x1, Tin, TH	Header 2x1
J2	1		1051330001	Molex	Connector, Receptacle, USB TYPE B, Vertical, TH	Connector, Receptacle, USB TYPE B, Vertical, TH
J4, J5	2		TFM-110-02-L-D-A	Samtec	Straight Low Profile Header, 10x2 Position,1.27 mm Pitch, SMT	10x2 SMT, 15.88x6.35x5.72mm
J6	1		LPPB061NFSC-RC	Sullins Connector Solutions	Receptacle, 1.27mm, 6x1, Gold, SMT	Receptacle, 1.27mm, 6x1, SMT
J7	1		0015910080	Molex	Header, 100mil, 4x2, Gold, SMT	Header, 100mil, 4x2, SMT
L1, L3	2	330 ohm	BLM18SG331TN1D	MuRata	Ferrite Bead, 330 ohm @ 100 MHz, 1.5 A, 0603	0603
L2	1		SRF2012-361YA	Bourns	Inductor, Wirewound, Ferrite, , 0.3 A, 0.45 ohm, SMD	2.0x1.2x1.2mm
L4	1	10uH	VLF252015MT-100M	TDK	Inductor, Shielded, Ferrite, 10uH, 0.47A, 0.24 ohm, SMD	IND_2.5x1.5x2mm
L5, L6	2	330 ohm	BLM18SG331TN1D	MuRata	1.5A Ferrite Bead, 330 ohm @ 100MHz, SMD	0603
Q1	1	50V	BSS138	Fairchild Semiconductor	MOSFET, N-CH, 50V, 0.22A, SOT-23	SOT-23
R1	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
R3, R5, R7, R8, R9, R10, R11, R12, R13, R14, R15	11	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402
R16, R17	2	4.99k	CRCW04024K99FKED	Vishay-Dale	RES, 4.99k ohm, 1%, 0.063W, 0402	0402
R18, R19, R20	3	47.5k	CRCW040247K5FKED	Vishay-Dale	RES, 47.5 k, 1%, 0.063 W, 0402	0402
R21	1	221	CRCW0402221RFKED	Vishay-Dale	RES, 221 ohm, 1%, 0.063W, 0402	0402
R22	1	10k	CRCW040210K0JNED	Vishay-Dale	RES, 10 k, 5%, 0.063 W, 0402	0402
		4.99k	CRCW04024K99FKED	Vishay-Dale	RES, 4.99 k, 1%, 0.063 W, 0402	0402

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R24, R25, R26,	4	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
R27						
S1, S2, S3	3		4-1437565-1	TE Connectivity	Switch, Tactile, SPST-NO, 0.05A, 12V, SMT	SW, SPST 6x6 mm
SH-J1, SH-J2, SH- J3, SH-J4, SH-J5, SH-J6	6	1x2	2SN-BK-G	Samtec	Shunt, 2mm, Gold plated, Black	2mm Shunt, Closed Top
TP1, TP2, TP3	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP4	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
TP5, TP6	2	Yellow	5009	Keystone	Test Point, Compact, Yellow, TH	Yellow Compact Testpoint
U1	1	_	TLV71333PDBV	Texas Instruments	Capacitor-Free, 150-mA, Low-Dropout Regulator with Foldback Current Limit for Portable Devices, DBV0005A	DBV0005A
U2	1		TPD2E2U06DRL	Texas Instruments	DUAL CHANNEL HIGH SPEED ESD PROTECTION DEVICE, DRL0005A	DRL0005A
U3	1		EA DOGM128W-6	Electronic Assembly	Module, 128x64-pixel graphics display	LCD Module
U4	1		LM3630ATME	Texas Instruments	LM3630A High-Efficiency Dual-String White LED Driver, YFQ0012AKAR	YFQ0012AKAR
U5, U6	2		TPD1E10B06DPYR	Texas Instruments	ESD in 0402 Package with 10 pF Capacitance and 6 V Breakdown, 1 Channel, -40 to +125 degC, 2-pin X2SON (DPY), Green (RoHS & no Sb/Br)	DPY0002A
U7	1		MSP430FR5969IRGZ	Texas Instruments	Mixed Signal Microcontroller, RGZ0048B	RGZ0048B
U8	1		HDC1000YPA	Texas Instruments	HDC1000 Low power integrated humidity and temperature Sensor, YPA0008AGAE	YPA0008AGAE
U9	1		OPT3001DNP	Texas Instruments	Ambient Light Sensor, DNP0006A	DNP0006A
U10	1		FDC1004DSC	Texas Instruments	4-Channel Capacitance-to-Digital Converter for Capacitive Sensing Solutions, DSC0010B	DSC0010B
C26, C27	0	18pF	GRM1885C2A180JA01D	MuRata	CAP, CERM, 18pF, 100V, +/-5%, C0G/NP0, 0603	0603
C32, C33, C34, C35	0		Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Used in PnP output
FID1, FID2, FID3, FID4, FID5, FID6	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
R2, R4, R6	0	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402
Y1	0		NX3225GD-8MHZ-STD-CRA-3	NDK	Crystal, 8MHz, 5pF, SMD	3.2x1.0x2.5mm

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